

# Dual 2:1 USB2.0 Mux/De-Mux with DC 30V Over-Voltage Protection

### **Descriptions**

The RLCS4000M is a bidirectional low-power dual port, high-speed, USB 2.0 analog switch with integrated protection for USB Type-C™ systems. The device is configured as a dual 2:1 or 1:2 switch. It is optimized for use with the USB 2.0 DP/DM lines in a USB Type-C™ system. The RLCS4000M integrated over-voltage protection on the C0+/- pins can withstand up to DC 30V with automatic shutoff circuitry in order to protect system components behind the switch. GPIO controls of SEL and \_EN are 1.8V logic compatible. The RLCS4000M is available in MSOP-10L with Pb-free and Halogen-free making it a perfect candidate for mobile and space constrained applications.

#### **Features**

- > Supply Range 2.5 V to 5.5 V
- Differential 2:1 or 1:2 Switch/Multiplexer
- ➤ Up to DC 30V Overvoltage Protection (OVP) on C0+/- Ports
- ➤ IEC 64000-4-5 Surge Protection w/o External TVS onto C0+/- Ports: ±30V
- System Side Clamp Voltage Pulse Less than 9V, Duration Less than 200nS
- Powered Off Protection When VDD = 0 V
- > Low RON of 10 Ω Typical
- Insertion loss: -1dB@200MHz, -2dB@650MHz, -3dB@1GHz
- ➤ C<sub>ON</sub> of 4.8 pF , 1.8-V Compatible Logic Inputs,
- Standard Temperature Range of 0°C to 85°C

#### **Applications**

- ➤ Anywhere a USB Type-C<sup>TM</sup> o
- Micro-B Connector is Used
- Mobile Phones,
- Tablets and Notebooks

#### **Functions and Pin Configuration**

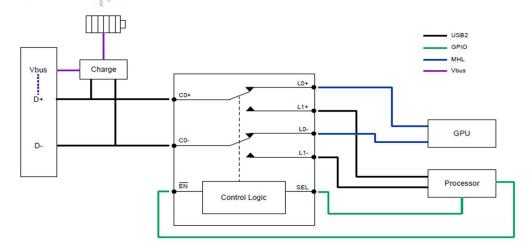


Fig.1 Functional Diagram



# **Pin Configuration**

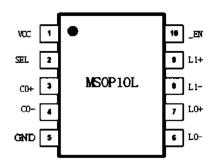


Fig.2 MSOP-10L

### **Pin Descriptions**

MSOP-10L	Pin Name	Signal Type	Description		
3	C0+	I/O	Signal I/O, Common Port		
4	C0-	I/O Signal I/O, Common Port			
9	L1+	I/O Signal I/O, Channle 1			
8	L1-	I/O Signal I/O, Channle 1			
7	L0+	I/O	Signal I/O, Channle 0		
6	LO-	I/O	Signal I/O, Channle 0		
2	SEL	I	Operation Model Select (when SEL=0: C0→L0, when SEL=1: C0→L1)		
10	_EN	I	_EN=1, Power Down is Enabled.		
1	VDD	PWR	Positive Supply Voltage		
5	GND	GND Power Ground			

Table-1 Pin Descriptions

# **Order Information**

Package		Part Number	Quantity Per Reel		
MSOP-10L	Tape and Reel	RLCS4000MS10/R6	3,000PCS		

Table-2 Order Information

# **Truth Table**

Function	SEL	_EN
C0+/- to L0+/-	L	L
C0+/- to L1+/-	Н	L
All Switches Hi-Z	X	Н

**Table-3 Truth Table** 



### Electrical Characteristics (Ta=25°C, VDD=3.3V, unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
POWER SUPPLY						
Supply Voltage Range	VDD		2.5	3.3	5.5	V
Committee Committee		_EN =1 disconnection		0.6	2	uA
Supply Current	Icc	_EN =0 connection		33		uA
SEL/_EN DIGITAL INPUT	CONTOL					
control input logic high	ViH		1.6		5.5	V
control input logic low	VIL		-0.1		0.5	V
Internal pull-down resistor	R <sub>PD</sub>			2		ΜΩ
SWITCH ON RESISTANCE	AND OFF L	EAKAGE				
On-Resistance	Ron	V <sub>IS</sub> = 0V~0.4V I <sub>OUT</sub> =8mA		10	11	Ω
Ron Flatness <sup>(1)</sup>	RFLAT	V <sub>IS</sub> = 0V~0.4V I <sub>OUT</sub> =8mA		0.3	0.5	Ω
R <sub>ON</sub> Matching Between Channels <sup>(2)</sup>	ΔR <sub>ON</sub>	V <sub>IS</sub> = 0V~0.4V I <sub>OUT</sub> =8mA		0.1	0.2	Ω
OFF Leakage Current	I <sub>LEAK</sub>	V <sub>C0+/-</sub> =10V V <sub>L1+/-</sub> = V <sub>D2+/-</sub> =0V	160	31	50	uA
SWITCH DYNAMICS	<u> </u>	><	30,	1.	27	
On Capacitance	Con	V <sub>C0+/-</sub> = 0.2V, f = 1MHz	10	4		pF
Off Capacitance	Coff	V <sub>C0+/-</sub> = 0.2V, f = 1MHz	2/2	3		pF
Off Isolation	Off	f=250MHz, R <sub>T</sub> =50Ω, C <sub>L</sub> = 0pF	(A)	-38		dB
Crosstalk <sup>(3)</sup>	V	f-050MH- D -500 0 - 0-5	o .	44		.ID
(Channel-to-Channel)	XTALK	f=250MHz, R <sub>T</sub> =50Ω, C <sub>L</sub> = 0pF		-41		dB
-3dB Bandwidth	BW	$R_T$ =50 $\Omega$ , $C_L$ =0pF Signal Power 0dBm	0.9	1		GHz
Break-Before-Make	BBM	$V_{L1+/-}=V_{D2+/-}=0.4V, R_{L}=50\Omega$		1.5		uS
Turn-on Time	toff	$V_{C0+/-} = 0.4V$ , $R_L=50\Omega$ _EN switches from High to Low		20		uS
Turn-off Time	toff	$V_{C0+/-} = 0.4V$ , $R_L=50\Omega$ _EN switches from Low to High		1.2		uS
Propagation Delay	t <sub>PD</sub>	$V_{C0+/-} = 0.4V$ , $R_L = 50\Omega$		200		pS
OVER VOLTAGE PROTECT	ION					-
OVP Lockout Threshold	Vove	V <sub>C0+/-</sub> Rising Edge	4.6	4.9	5.2	V
OVP Hysteresis	V <sub>HYS</sub>	V <sub>C0+/-</sub> Falling Edge		200		mV
Clamp Voltage on L1+/-	VCLAMP	10V shorts to C0+/-	6.5 8		8	V
and D <sub>2+/-</sub>	V CLAMP	with R <sub>L</sub> =1K $\Omega$ @ L1+/- and D <sub>2+/-</sub>			V	
OVP Response Time	t <sub>FP</sub>	10V shorts to C0+/- with $R_L$ =1K $\Omega$ @ L1+/- and $D_{2+/-}$		200	300	nS
OVP Recovery Time	t <sub>FPR</sub>	V <sub>C0+/-</sub> jumps from 6V to 1V step	30	45	60	uS

#### **Table-4 Electrical Characteristics**

### Note:

- (1) Flatness is defined as the difference between maximum and minimum value of ON-resistance at the specified analog signal voltage points.
- (2) R<sub>ON</sub> matching between channels is calculated by subtracting the channel with the lowest max Ron value from the channel with the highest max Ron value.
- (3) Crosstalk is inversely proportional to source impedance



#### Typical Performance Curves (Ta=25°C, VDD=3.0V, CAP=0.1uF, unless otherwise noted)



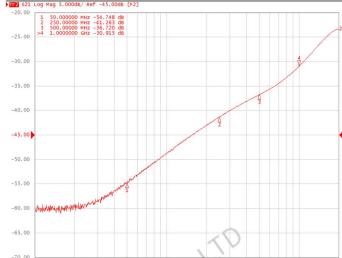


Fig.3 Switch Bandwidth or Insertion Loss

Fig.4 Switch Channel to Channel Cross-Talk

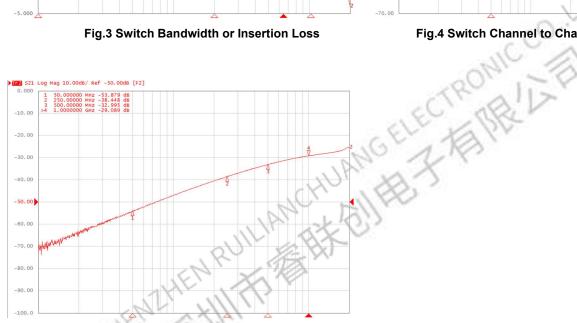
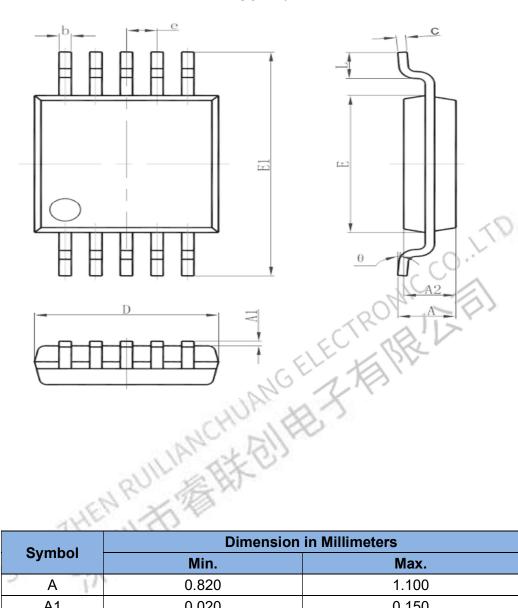


Fig.5 Switch Off Isolation



### **Package Outline Dimension**

### MSOP-10L



Symbol	Dimension in Millimeters			
Syllibol	Min.	Max.		
Α	0.820	1.100		
A1	0.020	0.150		
A2	0.750	0.950		
b	0.180	0.280		
С	0.090	0.230		
D	2.900	3.100		
е	0.50	0.50(BSC)		
E	2.900	3.100		
E1	E1 4.750 5.050			
L	0.400 0.800			
θ	0°	6°		

**Table-5 Package Dimension** 



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